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Table of contents

Conference Sessions

Session I: Design of smart integrated systems I

Self-powered sensors using parametric resonance16

Dr. Antony Rix, 8power ltd, UK

Self-powered Wireless Sensor Node24

Dr. Bogdan Rosinski, Thien Hoang, Claire Bantignies, Guillaume Ferin, VERMON SA, FR

A new approach to miniaturize high resolution linear position measurement systems28

Dr. Rolf Slatter, Dr. Johannes Paul, Sensitec GmbH, DE

System integration of printed biosensors for sweat electrolytes with data acquisition via Bluetooth to App36

Dr. Susanne Oertel, Michael Jank, Alicia Zörner, Fraunhofer Institute for Integrated Systems and Device Technology IISB, DE

Björn Schmitz, Nadine Lang, Fraunhofer Institute for Integrated Circuits IIS, DE

Session II: System integration and packaging I

3D Packaging Technologies for Smart Medical Implants41

Tim Schröder, Dirk Wuensch, Mario Baum, Karla Hiller, Maik Wiemer, Thomas Otto, Fraunhofer Institute for Electronic Nano Systems ENAS, DE

Jens Weidenmüller, Özgü Dogan, Alexander Utz, Michael Görtz, Fraunhofer IMS, DE

3D-MID Design and Manufacturing48

Manuel Martin, Beta LAYOUT GmbH, DE

Electrical feed through for tool integrated high temperature applications50

Folke Dencker, Felix Kolodziejczyk, Marc C. Wurz, Leibniz Universität Hannover, DE

Advanced passive optical alignment to meet the latest packaging requirements in photonic packagingN/A

Martin Rogge, Finetech GmbH & Co. KG, DE

Session III: Design of smart integrated systems II

CMOS-Design of a Cascadable Front-End ASIC for Capacitive Micromachined Ultrasonic Transducer (CMUT) Arrays59

Andreas Weder, Sandro Koch, Marcus Pietzsch, Andreas Heinig, Marco Kircher, Nicolas Lange, Jörg Amelung, Fraunhofer Institute for Photonic Microsystems (IPMS), DE

Sens-o-Spheres | A concept for location independent acquisition of process measurement signals67

Tobias Lüke, Maik-Julian Bükler, Christian Hedayat, Fraunhofer Institute for Electronic Nano Systems ENAS, DE

Felix Lenk, Tim Lauterbach, TU Dresden, DE

Tassilo Gernandt, Rüdiger Moll, Peter Buchner, IMST GmbH, DE

The Selectivity Measurements of Multi-channel, High Sensitivity Vapor Trace Detection System75

Prof. Drago Strle, University of Ljubljana, SL
Marion Van Miden, Igor Muševič, IJS, SL

SoC Low Differential Air Pressure Sensor81

Elias Kögel, Marco Ramsbeck, John Thomas Horstmann, Chemnitz University of Technology, DE

Session IV: System integration and packaging II

Interposer-based smartcard system with active wireless communication90

Fabian Hopsch, Andy Heinig, Mathias Böttcher, Fraunhofer Institute for Integrated Circuits IIS, DE

A novel Wafer-level Packaging Method for a Direct-Backside-Exposure Pressure Sensor anodically bonded to a Silicon-Interposer with a thin film Glass Layer98

Biswajit Mukhopadhyay, P. Mackowiak, O. Ehrmann, K.-D. Lang, M. Fritz, M. Bäuscher, H.-D. Ngo, Fraunhofer Institute for Reliability and Microintegration IZM, DE
Xiaodong Hu, Technical University of Berlin, DE
U. Hansen, S. Maus, O. Gyenge, MSG Lithoglas GmbH, Germany

UV LED custom interconnection for enhanced heat dissipation106

Dr. Sabine Nieland, Dennis Mitrenga, Dominik Karolewski, Olaf Brodersen, Thomas Ortlepp, CIS Forschungsinstitut für Mikrosensorik und Photovoltaik GmbH, DE

Hybrid sun sensors for pico satellite114

Dr. Nenad Marjanovic, Jérémy Disser, Frédéric Zanella, Jürg Schleuniger, Alessandro Mustaccio, Rolando Ferrini, Marc Schnieper, CSEM SA, CH
Eyad Assaf, HIGHTEC MC AG, CH

Session V: Low cost approaches

Designing of a semi-transparent Electroluminescent Umbrella123

Prof. Kaspar Jansen, Stan Claus, Bahar Barati, Delft University of Technology, NL

Chemical Sensors on PaperN/A

Prof. Dr. Yvonne Joseph, TU Bergakademie Freiberg, DE

Manufacturing of all-inkjet-printed electronic devices on flexible polymer substratesN/A

Enrico Sowade, Chemnitz University of Technology, DE

Session VI: Test and reliability

Fingerprinting MEMS Gyroscopes133

Oliver Willers, Michael Curcic, Robert Bosch GmbH, DE
Helmut Seidel, Saarland University, DE

Smart Analyzer Systems for Emission MeasurementsN/A

Dr. Andreas Klug, AVL LIST GmbH, AT

Reliability characterization of aerosol jet printing technology for multilayer secure envelopes142

Dr. Aurelien Lecavelier, Thales Global Services, FR

Session VII: Perspectives of smart systems

A wafer-level MEMS-LSI integration platform using fly-cut bonding metals customizable for diverse applications151

Hideki Hirano, Yukio Suzuki, Rakesh Chand, Shuji Tanaka, Tohoku University, JP

Single-use paper fuel cells and batteries for disposable Point of Care devices159

Prof. Neus Sabaté, Juan Pablo Esquivel, Institute of Microelectronics of Barcelona IMB-CNM, ES

Smart Systems Integration in the era of Solid State Lighting160

Dr. Willem van Driel, G.Q. Zhang, H. van Zeijl, R. Poelma, Z.K. Esfahani, M. R.Venkatesh, L. Middelburg, B. El Mansouri, Delft University of Technology, NL

Session VIII: Smart systems applications

Unobtrusive energy harvesting of human body heat166

Moritz Thielen, Christofer Hierold, ETH Eidgenössische Technische Hochschule Zürich ETH Zentrum, CH

3D Ranging and Tracking Using Lensless Smart Sensors172

Dr. Lizy Abraham, Andrea Urru, Mariusz Wilk, Salvatore Tedesco, Brendan O'Flynn, University College Cork Tyndall National Institute, IE

Development of an Integrated Sensing System for PAT Application in the Food and Beverage Industry180

Shauna Scanlon, Eric Moore, University College Cork Tyndall National Institute, IE
Sharon Rothwell, PepsiCo International, IE

Smart System Integration for Digital Water infrastructure190

Cees J.M. Lanting, DATSA Belgium, BE
Antonio Lionetto, STMicroelectronics, IT

Session IX: New materials for nano structures and devices

Nanocomposite Materials for Miniaturized Supercapacitors199

Qi Li, Volodymyr Kuzmenko, Mazharul Haque, Per Lundgren, Elof Köhler, Henrik Staaf, Peter Enoksson, Chalmers University of Technology, SE

Smart HVAC Sensors for Smart Energy206

Dr. Jamila Boudaden, F. Wenninger, A. Klumpp, I. Eisele, C. Kutter, Fraunhofer Research Institution for Microsystems and Solid State Technologies EMFT, DE

Thermoelectric Micropower Source based on Si Nanowires213

Dr. Luis Fonseca, Carlos Calaza, Inci Donmez, Marc Salleras, Instituto de Microelectrónica de Barcelona IMB-CNM (CSIC), ES
Gerard Gadea, Jose D. Santos, Alex Morata, Albert Tarancón, Catalonia Institute for Energy Research (IREC), ES

Novel negative tone spray-coatable photoresist for photolithography processing over high topographical steps217

Markus Arnold, Sven Haas, Falk Schwenzer, Gunther Schwenzer, Danny Reuter, Karla Hiller, Chemnitz University of Technology, DE
Anja Voigt, Gabi Gruetzner, micro resist technology GmbH, DE

Session X: Success stories

Metal oxide based smart electronic nose resilient to air humidity changes226

Dr. Raimund Leitner, Matic Krivec, CTR Carinthian Tech Research AG, AT
Dieter Maier, Roland Waldner, Philips, AT
Florian Überall, Innsbruck University, AT

ENGIDI an ICT solution for Personal Protective Equipment233

Dr. Sergio Martínez Navas, LEITAT, ES
Gerard Fernández Curell, ENGIDI Company, ES

Grid-EYE – Thermopile Array Sensor and The Internet of Things239

Mubeen Abbas, Panasonic Automotive & Industrial Systems Europe GmbH, DE

Personalization of phlebotomy using smart systems integration247

Dr. Markus Riester, meisterwerk ventures GmbH, DE
Jörn Bungartz, midge medical GmbH Berlin, DE

Session XI: Smart medtech systems

Implantable wireless pressure sensor253

Alfred Binder, Pascal Nicolay, Martin Lenzhofer, CTR Carinthian Tech Research AG, AT
Wolfgang Stocksreiter, FH JOANNEUM, AT
Peter Schlumpf, Venjamin Stojanov, UNISENSOR, CH

MoniShirt – Large area printed piezoelectric sensors for body motion tracking261

Thomas Knieling, Ram Kumar Raja Mahendra Varman, Fraunhofer Institute for Silicon Technology ISIT, DE
Timo Grunemann, Gerhard Domann, Fraunhofer ISC, DE

Smart system for light treatment of chronic wounds269

David Kallweit, J. Mayer, O. Fernandez, R. Ferrini, CSEM SA, CH
A. Klapczynski, N. Kuch, A. Becker, N. Gretz, University of Heidelberg, DE
J. Steinbrunn, M. Bouschbacher, URGO Recherche Innovation et Développement (URGO RID), FR
K. Michaelides, SignalGenerix, CY
R. Waite, MicroSemi, UK
D. Manassis, M. Seckel, Technical University of Berlin, DE

The "Smart" Needle – A Needle Integrated with an Impedance Sensor for Objective Nerve Localisation during Ultrasound Guided Peripheral Nerve Block275

Lisa Helen, Brian O'Donnell, Walter Messina, and Eric Moore, University College Cork Tyndall National Institut, IE

Design and fabrication of two types of tapered waveguides for evanescent sensing282

Yu Xin, Gregory Pandraud, Paddy French, Technology University Delft, NL
Yongmeng Zhang, MEMS lab, CN

Session XII: Manufacturing of smart systems

Roll-to-Roll processed foil inlay as an electrostatic chuck for flexible thin semiconductor wafer handling290

Indranil Ronnie Bose, Patrick Gest, Christof Landesberger, Christoph Kutter, Fraunhofer Research Institution for Microsystems and Solid State Technologies EMFT, DE

Heterogeneous integration of telecom lasers to Si substrates by micro transfer printing298

Ruggero Loi, James O'Callaghan, Brendan Roycroft, Agnieszka Gocalinska, Enrica Mura, Emanuele Pelucchi, Tyndall National Institute, IE
Antonio Jose Trindade, Alin Fecioru, Christopher A. Bower, Brian Corbett, X-Celeprint Ltd, IE

A Novel Process Module for Inertial Sensor Open Platform TechnologyN/A

Uwe Schwarz, X-FAB MEMS Foundry GmbH, DE

Development of a patterning process for releasing and sealing of post-CMOS MEMS pressure sensor membranes306

Christian Walk, Nino Vidovic, Michael Görtz, Holger Vogt, Fraunhofer Institute for Microelectronic Circuits and Systems, DE

DC-DC Step-down Micromodule with Embedded Inductor for Point-of-load Power Applications314

Dragan Dinulovic, Michael Brooks, Martin Haug, Würth Elektronik eiSos GmbH & Co. KG, DE

Session XIII: Advanced micro and nano technologies

Micro-Transfer-Printing for displays based on inorganic LEDs322

António José Trindade, Alin Fecioru, Steven Kelleher, Raja Gul, X-Celeprint Ltd., IE
Erich Radauscher, Salvatore Bonafede, David Gomez, Tanya Moore, Carl Prevatte,
Brook Raymond, Brent Fisher, Kanchan Ghosal, David Kneeburg, Matthew Meitl,
Christopher Bower, X-Celeprint Inc., US

An opto-chemical CO₂ sensor system based on new Sol-Gel Films328

Dr. Andreas T. Winzer, N. Thronicke, S. Nieland, Th. Ortlepp, CIS Forschungsinstitut für Mikrosensorik und Photovoltaik GmbH, DE

High frequency GaN/Si SAW devices for pressure sensing336

Dr. Alexandru Muller, IMT Bucharest, RO

Application of smart microsystem based technology for food, beverage, environment, security and health monitoring337

Dr. Eric Moore, Walter Messina, Patricia Vazquez, Anna Hogan, Gerard Duffy, Lisa Helen, Niall Savage, Shauna Scanlon, Yineng Wang, Xi Cao, Shifa Felemban, Thanih Balbaied, Michelle Fitzgerald, University College Cork Tyndall National Institute, IE
Bill Bennett, Martin O'Sullivan, BreastCheck & Cork University Hospital, IE
Brian O'Donnell, Cork University Hospital, IE

Feasibility of manufacturing packaged electronic systems by thermoset injection molding345

Romit Ashok Kulkarni, D. Hera, T. Günther, T. Grözinger, A. Zimmermann, Hahn-Schickard-Gesellschaft für angewandte Forschung e.V. HSG-IMAT, DE
M. Soltani, Institut für Mikrointegration, DE

Poster Session

Reliable Design of Thermally Actuated RF-MEMS Switch for Operation in Low-Gigahertz Band355

Angela Baracu, Valentin Buiculescu, George Boldeiu, Raluca Müller, National Institute for Research and Development in Microtechnologies, RO

Knee Symmetry Analyser359

Marco Belcastro, Brendan O'Flynn, James Maher, Kevin Hurley, Tyndall National Institute, IE

Hydrodynamic characterisation of micro-gaps and microchannels for the thermal control of Photonic Integrated Circuits (PICs)363

Marian Carroll, Jeff Punch, Eric Dalton, Niamh Richardson, Stokes Laboratories, University of Limerick, IE

Portable System for Visual Evoked Potentials Monitoring367

Prof. Danilo Demarchi, Politecnico di Torino, IT
Alessandro Sanginario, Electronic Design Laboratory, Genova, Italy
Paolo, Astengo, ASTEL Srl, IT
Antonio, Melcarne, Carola Vera, Junemann, S.C. Neurochirurgia – Città della Salute e della Scienza, IT

Trench Filling With a-Si Using a PE-CVD Deposition and Back Etch Sequence370

Linus Elsässer, Andreas Naumann, Fraunhofer Institute for Photonic Microsystems (IPMS), DE

Elastomer Stamp Lifetime and Process Capability in Micro Transfer Printing374

Dr. Alin Mihai Fecioru, António Jose Trindade, Raja Fazan Gul, Steven Kelleher, X-Celeprint Ltd., IE
David Gomez, Matthew A. Meitl, Salvatore Bonafede, Carl Prevatte, Tanya Moore, , and Christopher A. Bower, X-Celeprint Inc., IE

Results of multi-mass high precision vibratory MEMS gyroscopes for two types of system approaches378

Dr. Maxim Fedorov, Irina Popova, Alexander Lestev, Oleg Rakityansky, Vladimir Ivanov, Andrey Semenov, JSC Gyrooptics, Saint-Petersburg, RU
Roman Forke, Alexey Shaporin, Karla Hiller, Fraunhofer ENAS, DE
Daniel Koehler, Stefan Konietzka, EDC GmbH, DE

Lead-free piezoelectric MEMS cantilever for energy harvesting - design, optimization and technologyN/A

Bogdan Firtat, National Institute for R&D in Microtechnologies, RO

Reliability of thermo sonic flip chip bonded pressure sensors with through silicon via383

Dr. Thomas Frank, Andrea Cyriax, Michael Blech, Andre Grün, Stefan Jagomast, Manuel Kermann, Sebastian Pobering, Robert Täschner, Stefan Völlmeke, Heike Wünscher, Thomas Ortlepp, CIS Forschungsinstitut für Mikrosensorik und Photovoltaik GmbH, DE

Long-term stability of the assembled silicon strain gauge for precision measurements386

Dr. Thomas Frank, Andre Grün, Stefan Jagomast, Andrea Cyriax, Daniel Schäffler, Arndt Steinke, Thomas Ortlepp, CIS Forschungsinstitut für Mikrosensorik und Photovoltaik GmbH, DE
Dietmar Arndt, ADZ NAGANO, Ottendorf-Okrilla

Filling of high aspect ratio (HAR) nanometer-scale silicon trenches by electrochemical deposition of nickel391

Christian Hofmann, Florian Kurth, Maik Wiemer, Thomas Otto, Fraunhofer Institute for Electronic Nano Systems, DE
Karla Hiller, Chemnitz University of Technology, DE

Integration of self-healing agent into MEMS bonding frames395

Florian Kurth, C. Hofmann, S. Hertel, P. Braun, T.J. Schroeder, M. Wiemer, Fraunhofer Institute for Electronic Nano Systems, DE

LED packaging with optimized heat dissipation for a micro LED array399

Alexander Kusch, Marc Wurz, Leibniz Universität Hannover, DE
Marcel P. Held, Alexander Wolf, Roland Lachmayer, Leibniz Universität Hannover, DE

Efficient thermal management of photonic device using micro thermoelectric coolers403

Swatchith Lal, Kafil M. Razeeb, University College Cork Tyndall National Institute, IE

Influence of processing atmosphere for QD-LEDs407

Jörn Langenickel, T.Otto, Chemnitz University of Technology, DE
A.Weiß, Fraunhofer Institute for Electronic Nano Systems, DE

INSPEX: Integrated Smart Spatial Exploration System411

Dr. Suzanne Lesecq, L. Ouvry, CEA, LETI, MINATEC Campus, FR
M. Correvon, G. Dudnik, CSEM SA, CH
J. Barrett, A. McGibney, Cork Institute of Technology, IE
F. Birot, H. de Chaumont, GoSense Lyon, FR
R. Banach, Univ. of Manchester, UK
J.-M. Van Gyseghem, J. Herveg, Univ. of Namur, BE
C. Jackson, S. Buckley, SensL, IE
A. di Matteo, V. di Palma, STMicroelectronics Srl, IT
C. Ó'Murchú, A. Mathewson, Tyndall National Institute, IE

3D printing in silicon415

Latifa Louriki, P. Staffeld, A. Kaelberer, Robert Bosch GmbH, DE
T. Otto, R. Streiter, Technical University Chemnitz, DE

GIFT: a "Generic Integrated Forensic Toolbox" using a novel micro capillary electrophoresis device for rapid separation and detection of organophosphate nerve agents419

Dr. Walter Messina, Yineng Wang, Xi Cao, Annamaria Hogan, Eric Moore, University College Cork Tyndall National Institute, IE
Ed van Zalen, Netherlands Forensic Institute, NL

Detection of mechanical loads in lightweight structures using quantum dots photoluminescence423

Martin Möbius, M. Hartwig, R. R. Baumann, T. Otto, Chemnitz University of Technology, DE
J. Martin, Fraunhofer Institute for Electronic Nano Systems (ENAS), DE

Smart microsystem for dangerous gases detectionN/A

Dr. Carmen Moldovan, IMT-Bucharest, RO

Interface Power-Transfer Conditions for Piezoelectric Energy Harvesting on Damped Waves428

Martin Nielsen-Lönn, Atila Alvandpour, Linköping University, SW

The Internet of Plants: Sensing Plant Growth Parameters for Autonomous Greenhouse Control432

Brendan O'Flynn, Mariusz Wilk, Tyndall National Institute, IE
Oisín Dwane, Samuel O'Connell, University College Cork, IE

Thermally Integrated Smart Photonic Systems436

Dr. Cian Ó Murchú, University College Cork Tyndall National Institute, IE
Alexandre Shen, III-V Lab, FR
Ryan Enright, Nokia, IE
Kornelius Nielsch, IFW Dresden, DE
Romain Bachelet, CNRS, FR
Arne Leinse, LioniX, NL
Gabriel Charlet, Nokia, FR,
Jeff Punch, Stokes Institute, IE
Colm O'Riordan, Communicraft, IE
Kafil M. Razeeb, Tyndall National Institute, IE

Thermo-Mechanical and Mechanical Robustness of the INCOBAT Smart Battery Management System439

A. Otto, S. Rzepka, Fraunhofer Institute for Electronic Nano Systems, DE
R. Döring, L. Scheiter, Chemnitzer Werkstoffmechanik GmbH, DE
E. Armengaud, AVL List GmbH, DE

Robust vibration sensor for condition monitoring in railway applications443

Michael Pleul, Robert Schulze, Christoph Meinecke, Danny Reuter, Chemnitz University of Technology, DE
Petra Streit, Fraunhofer Institute for Electronic Nanosystems ENAS, DE
Kathrin Polster, Andreas Schuh, Lenord, Bauer & Co. GmbH, DE

Transfer Printing of Photovoltaic Power Converter447

David Quinn, James O'Callaghan, Brendan Roycroft, Ruggero Loi, John Justice, Agnieszka Gocalinska,
Emanuele Pelucchi, Brian Corbett, Tyndall National Institute, IE
Antonio Jose Trindade, Christopher A. Bower, X-Celeprint Limited, IE

Open IoT platform for luminary controls and smart cities sensing services451

Jordi Ricart, LEITAT, ES
Sergi Somavilla López, SECE Company, ES

IR Imaging of Laser Structures for Thermal Control of Photonics Integrated Circuits (PICs)455

Niamh Richardson, Jeff Punch, Eric Dalton, Marian Carroll, Stokes Laboratories, University of Limerick, IE

Developing Smart Sensing Systems for the Detection of Nutrients in Water459

Patrick Roche, Eoin Murray, T.E. Laboratories Ltd., IE

Development of sensor integration concept for mass production processes463

Florian Rost, Benjamin Arnold, Prof. Sven Rzepka, Fraunhofer Institute for Electronic Nano Systems, DE
Ricardo Decker, Angelika Bauer, Alexander Tsapkolenko, Lothar Kroll, Jan Mehner, Technische Universität
Chemnitz, DE

Effective viscoelastic plastic material modeling for faster and reliable calculations467

Florian Schindler-Saefkow, Remi Pantou, Sven Rzepka, Fraunhofer Institute for Electronic
Nano Systems, DE
Juergen Keller, AMIC Angewandte Micro-Messtechnik GmbH, DE

Inductive temperature measurement for fast and optimized adhesive curing471

Dominik Schröder, Maik-Julian Büker, Christian Hedayat, Fraunhofer Institute for Electronic
Nano Systems, DE
Malte Kleemeier, Andreas Lühring, Fraunhofer IFAM, DE

Increase of functional density of hybrid structures by integration of micro and nano systems475

Martin Schüller, Thomas Otto, Fraunhofer Institute for Electronic Nano Systems, DE
Jan Mehner, Juergen Troeltzsch, Lothar Kroll, TU Chemnitz, DE

Investigations on Parylene C for its Integrability into MEMS479

Franz Selbmann, Mario Baum, Frank Roscher, Tom Enderlein, Maik Wiemer, Thomas Otto, Fraunhofer
Institute for Electronic Nano Systems ENAS, DE
Prof. Yvonne Joseph, Christine Hecker, Technische Universität Bergakademie, DE

Supercapattery: A Hybrid Energy Storage Device for the Next Generation Pacemaker483

Han Shao, Padman Narayanasamy, David McNulty, Colm O'Dwyer, Kafil M. Razeeb, Tyndall National
Institute, IE

Novel concept of integrated micro actuation of membranes in liquid environments487

Cornelia Stiehl, Technical University Chemnitz, DE
Tom Enderlein, Thomas Otto, Fraunhofer Institute for Electronic Nano Systems, DE
Joerg Nestler, BiFlow Systems GmbH, DE

Smart sensor for pneumatic combined clutch and brake491

M. Tijero, Kepa Mayora, J. Berganzo, I. Aramburu, E. Arroyo-Leceta, Ikerlan-IK4, ES
M. Anasagasti, M. Mondragón, Goizper, ES.
D. Hoffmann, D. Stojakov, Hahn-Schickard, DE

Does this water make you sleepy? Testing in-situ Chloroform presence in drinking water495

Dr. Patricia Vazquez, Eric Moore, University College Cork Tyndall National Institute, IE
Maria Tijero, IKERLAN, ES
Mark Karle, Jan Dehnert, Hahn-Schickard, DE
Richard Crotty, Noel Gilmore, Brendan Murray, Environmental Laboratory Services Limited, IE

Wide-Field Epiretinal Stimulator with Adjustable Curvature499

Florian Waschkowski, W. Mokwa, RWTH Aachen, DE

Low-Cost Antenna Efficiency Measurement System for Smart System Antenna Efficiency Characterization503

Mark Whooley, John Buckley, Adolfo Di Serio, Donal O'Sullivan, Brendan O'Flynn, Tyndall National Institute, IE

Micro Sensor for Detecting the Direction of Incoming Light507

Dr. Andreas T. Winzer, D. Mitrenga, M. Schädel, S. Völlmeke, K.-D. Preuß, S. Nieland,
O. Brodersen, CIS Forschungsinstitut für Mikrosensorik und Photovoltaik GmbH, DE